



Product Change Notification

Change Notification #: **115948 - 01**

Change Title: **Intel® Gigabit CT Desktop Adapter,
Product Code: EXPI9301CT, MM#893646;
Product Code: EXPI9301CTBLK, MM#893647
Intel® Gigabit CT2 Desktop Adapter,
Product Code: E1G31CTG1P20, MM#908804
Intel® Ethernet Converged Network Adapter
X520-DA1, Product Code: E10G41BTDAPG1P5,
MM#927066
Intel® Ethernet Converged Network Adapter
X520-DA2, Product Code: E10G42BTDAPG1P5,
MM#927067
Intel® Ethernet Converged Network Adapter
X550-T1,
Product Code: X550T1, MM#940116;
Product Code: X550T1BLK, MM#940125;
Product Code: X550T1G1P5, MM# 940262
Intel® Ethernet Converged Network Adapter
X550-T2,
Product Code: X550T2, MM#940128;
Product Code: X550T2BLK, MM#940136;
Product Code: X550T2G1P5, MM#940263,
PCN **115948-01**, Label, Product Marking,
Product Material,
Label Update,
**Reason for Revision: Removal of Intel® Ethernet
Server Adapter I210-T1 Products from Affected
Products.****

Date of Publication: **December 13, 2017**

Key Characteristics of the Change:

Label, Product Marking, Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Dec 15, 2017
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Description of Change to the Customer:

Reason for Revision: Removal of Intel® Ethernet Server Adapter I210-T1 products from affected products.

These Intel products listed in both Products Affected tables below will undergo the following changes:

1. The Taiwan BSMI has a new RoHS declaration and inspection mark.
 - The BSMI logo will be updated on the board level, with a cover up label, and on the packaging label if it currently exists there.

Current



D33025

New



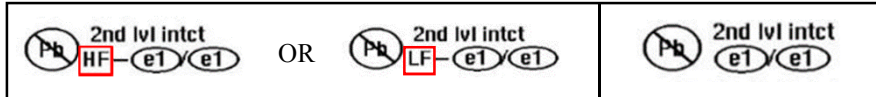
D33025
RoHS

2. Ukraine has a new RoHS declaration that will be added to the outer box packaging label.



3. In order to align all our products and labels with the JEDEC 609A Standard for board assembly marking, we will remove the HF or LF (as applicable) from all outer box packaging labels if it currently exists there.

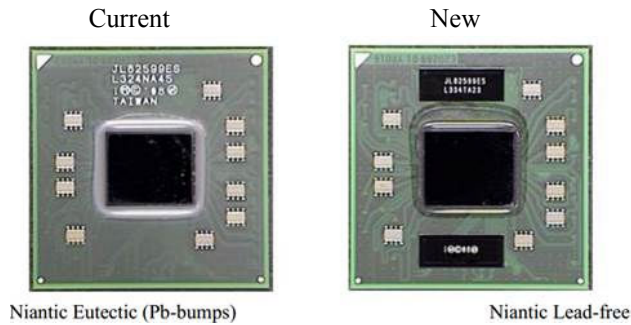
Current



New

Intel products Product Code: E10G41BTDAPG1P5, MM# 927066 and Product Code: E10G42BTDAPG1P5, MM# 927067, listed in the second Products Affected table below will undergo the following additional changes:

- As per the Intel Corporate Green Initiative, Intel is moving its products to a RoHS Compliant 100% lead-free process which impacted several of the flip-chip silicon product lines. The current silicon products are listed as 'exempt' based on the EU RoHS exemption for FLI leaded parts. This change removed that RoHS exemption. There is no impact on the silicon's function, electrical performance, mechanical use or stated reliability. Intel has qualified and certified this change in the same way as all products supplied to our customers. There is no form-fit-function change for any of the impacted silicon. FLI (First Level Interconnect) material will change from Lead (Pb) based solder bump technology to Pb-Free (Sn/Ag) technology. There is no change to the second level interconnects for these products. This change affects First Level Interconnects only. The transition from eutectic to lead free at the FLI style of the product marking will change. The mark will go to a laser mark on swatch versus an ink stamp on substrate as illustrated below.
- As a result of these changes, the PBA (printed board assembly) and TA (top assembly) numbers will roll as noted in the second affected products table within this PCN. If the PBA/TA numbers are printed on any product or box labels, those will show the PBA/TA dash roll as well.



Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers. The customer can expect to receive mixed inventory.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

Product code	MM#	TA	PBA
X550T2G1P5	940263	H92727-002	H49289-010
X550T1G1P5	940262	H92735-002	H89173-005
X550T2BLK	940136	H99164-002	H86377-005
X550T1BLK	940125	H99159-002	H92506-004
X550T1	940116	H92760-002	H92506-004
X550T2	940128	H92776-002	H86377-005
E1G31CTG1P20	908804	G10052-006	E99791-005
EXPI9301CT	893646	E39199-010	E46981-008
EXPI9301CTBLK	893647	E39203-010	E46981-008

Products Affected / Intel Ordering Codes:

Product code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
E10G41BTDAPG1P5	927066	G83817-004	G83818-004	G83817-005	G83818-005
E10G42BTDAPG1P5	927067	G83820-003	G83821-003	G83820-004	G83821-004

**Removed from PCN115948-01 Products / Intel Ordering Codes:
See instead PCN115991-00**

Product code	MM#	TA	PBA
I210T1G1P20	921435	G79024-006	G59947-010
I210T1BLK	921434	G86594-003	G69016-003
I210T1	921433	G86562-004	G69016-003

PCN Revision History:

Date of Revision:

November 29, 2017

December 13, 2017

Revision Number:

00

01

Reason:

Originally Published PCN

Removal of Intel® Ethernet Server Adapter
I210-T1 products from affected products.



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmopcn@intel.com

Asia Pacific/PRC Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jccb.ijkk@intel.com

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